

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended) A method for mounting through an adhesive sheet an electronic component on a printed circuit board provided with a wiring pattern, the method comprising the steps of:
placing the adhesive sheet on the wiring pattern so as to leave a space between the adhesive sheet and the printed circuit board;
heating air within the space intervening between the adhesive sheet and the printed circuit board; and
bonding, while heating the air, the adhesive sheet to an area of the printed circuit board to be mounted with the electronic component.
2. (previously presented) The method according to claim 1, wherein the air intervening between the adhesive sheet and the printed circuit board is heated upon heating the printed circuit board.
3. (previously presented) The method according to claim 2, wherein the electronic component is pressurized and bonded on to the adhesive sheet after the printed circuit board bonded with the adhesive sheet is cooled.
4. (previously presented) The method for mounting the electronic component according to claim 1, wherein temperature of the heating process is set to a range between equal to or higher than 60 degrees Celsius and equal to or lower than a reaction temperature of the adhesive sheet.

5. (previously presented) The method for mounting the electronic component according to claim 1, wherein the adhesive sheet is made of an anisotropic conductive film.

6. (previously presented) The method for mounting the electronic component according to claim 1, wherein the printed circuit board is made of a flexible board.